

262 High Power LaserMount



- 0.25°C/W passive cooling efficiency
- Customizable heat sink

Passive Cooling

The 262 LaserMount was designed for high power devices not requiring full active temperature control, but still needing significant passive cooling to maintain the device temperature near ambient. With its large heat sink and integrated fan, the 262 can handle high thermal loads with a 0.25°C/W temperature rise.

Device Cover

Beyond the mount itself, the 264 works with our optional device cover:



The **260-C** cover enhances the stability of the laser by minimizing the impact of ambient air currents.

Customized Device Support

The heat sink on the 262 can be customized to work with your device. Typically all that is needed is the data sheet for your device. Contact the factory for details and a price quote on customization.

Specifications

Laser Package Supported	Various, contact factory
Thermal resistance (°C/W)	0.25
Input connectors	
Laser Diode	DB-9, male or 9W4, male
Laser TEC	DB-15, male
General	
Size (H x W x D) [in(mm)]	3.0 (76.2) x 4.5 (114.3) x 6.0 (152.4)
Mounting holes	¼-20 x 4